

Description

The HSM10N15A is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

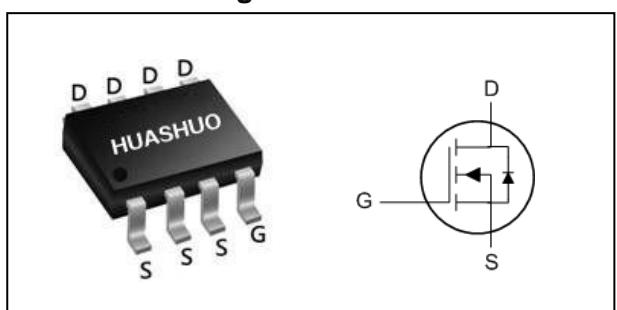
The HSM10N15A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

Product Summary

| | | |
|-----------------------|-----|----|
| V _{DS} | 150 | V |
| R _{DSON,typ} | 35 | mΩ |
| I _D | 10 | A |

SOP-8 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|---------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 150 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 10 | A |
| I _D @T _C =100°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 8 | A |
| I _D @T _A =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 5 | A |
| I _D @T _A =70°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 3.8 | A |
| I _{DM} | Pulsed Drain Current ² | 50 | A |
| P _D @T _A =25°C | Total Power Dissipation ³ | 2.7 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-ambient ¹ | --- | 85 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | --- | 23 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------------------------|--|---|------|------|-----------|------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$ | 150 | --- | --- | V |
| $\text{R}_{\text{DS(ON)}}$ | Static Drain-Source On-Resistance ² | $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=4\text{A}$ | --- | 35 | 56 | $\text{m}\Omega$ |
| $\text{V}_{\text{GS(th)}}$ | Gate Threshold Voltage | $\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$ | 2 | --- | 4 | V |
| I_{DSS} | Drain-Source Leakage Current | $\text{V}_{\text{DS}}=120\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^\circ\text{C}$ | --- | --- | 1 | μA |
| | | $\text{V}_{\text{DS}}=120\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=55^\circ\text{C}$ | --- | --- | 5 | |
| I_{GSS} | Gate-Source Leakage Current | $\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $\text{V}_{\text{DS}}=5\text{V}$, $\text{I}_D=4\text{A}$ | --- | 25 | --- | S |
| Q_g | Total Gate Charge | $\text{V}_{\text{DS}}=75\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=4\text{A}$ | --- | 23 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 5.8 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 4.2 | --- | |
| $\text{T}_{\text{d(on)}}$ | Turn-On Delay Time | $\text{V}_{\text{DD}}=75\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_G=3.3\Omega$ | --- | 16 | --- | ns |
| T_r | Rise Time | | --- | 18.6 | --- | |
| $\text{T}_{\text{d(off)}}$ | Turn-Off Delay Time | | --- | 28.5 | --- | |
| T_f | Fall Time | | --- | 6.5 | --- | |
| C_{iss} | Input Capacitance | $\text{V}_{\text{DS}}=75\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 1190 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 73 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 4 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------------------|------------------------------------|---|------|------|------|------|
| V_{SD} | Diode Forward Voltage ² | $\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_S=1\text{A}$, $\text{T}_J=25^\circ\text{C}$ | --- | --- | 1.2 | V |
| t_{rr} | Reverse Recovery Time | $\text{I}_F=4\text{A}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$, | --- | 45 | --- | nS |
| Q_{rr} | Reverse Recovery Charge | $\text{T}_J=25^\circ\text{C}$ | --- | 138 | --- | nC |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

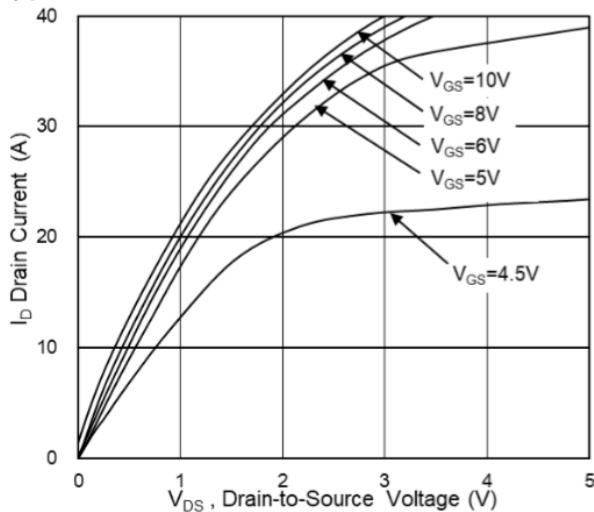


Fig.1 Typical Output Characteristics

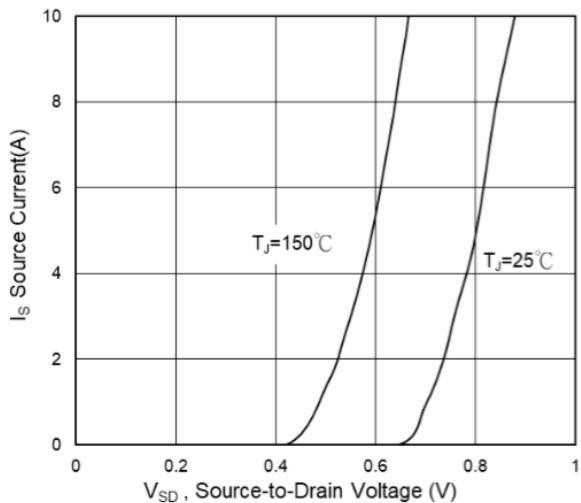


Fig.3 Forward Characteristics of Reverse

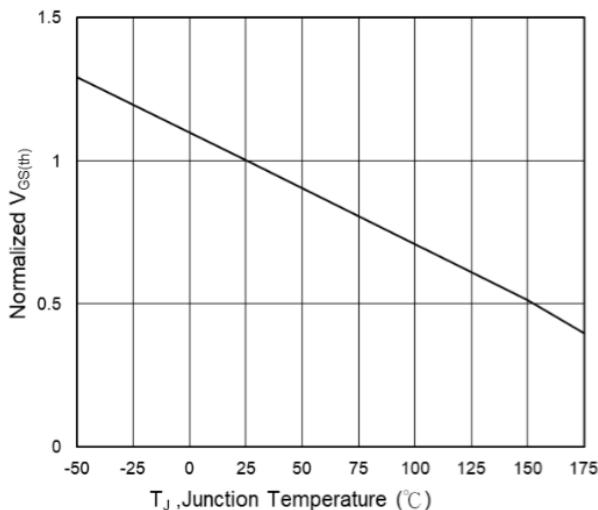


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

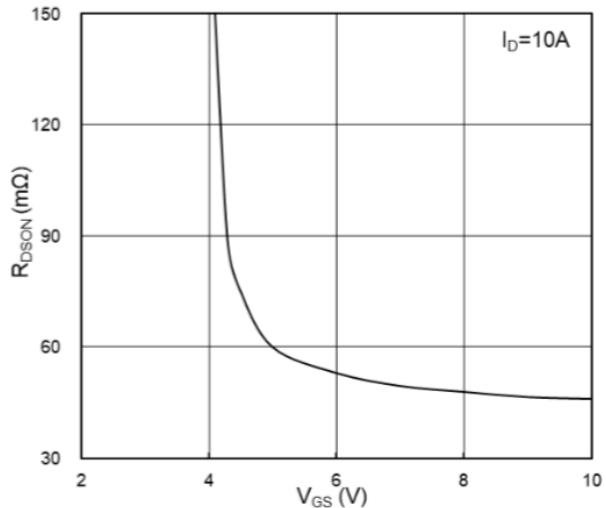


Fig.2 On-Resistance vs. Gate-Source Voltage

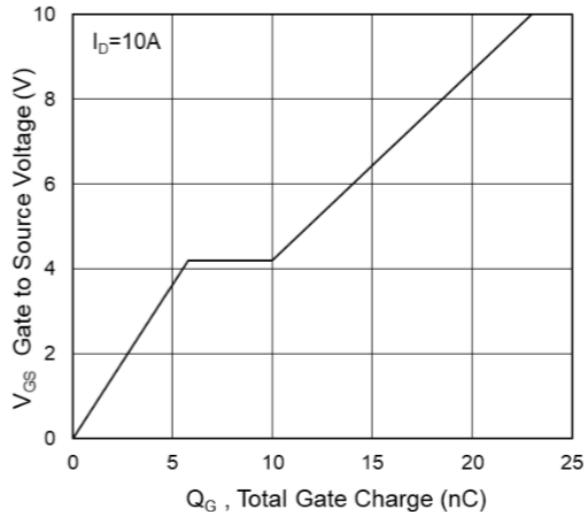


Fig.4 Gate-Charge Characteristics

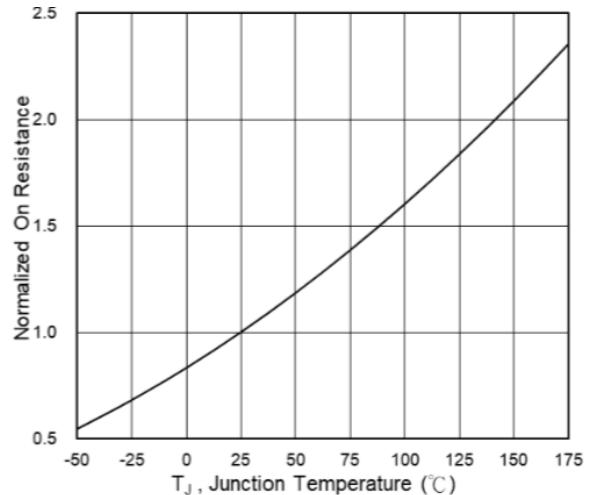


Fig.6 Normalized $R_{DS(on)}$ vs. T_J



HUASHUO
SEMICONDUCTOR

HSM10N15A

N-Ch 150V Fast Switching MOSFETs

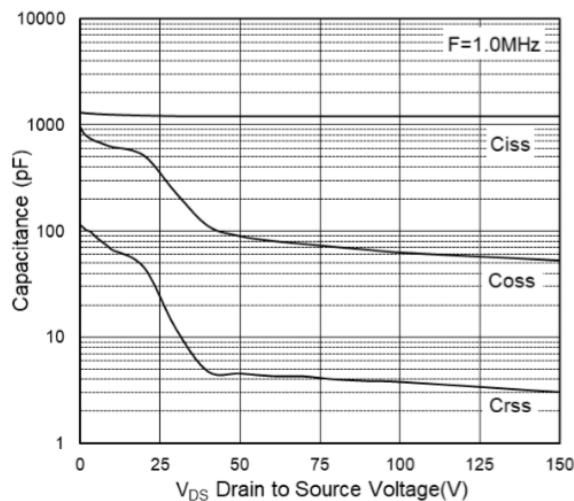


Fig.7 Capacitance

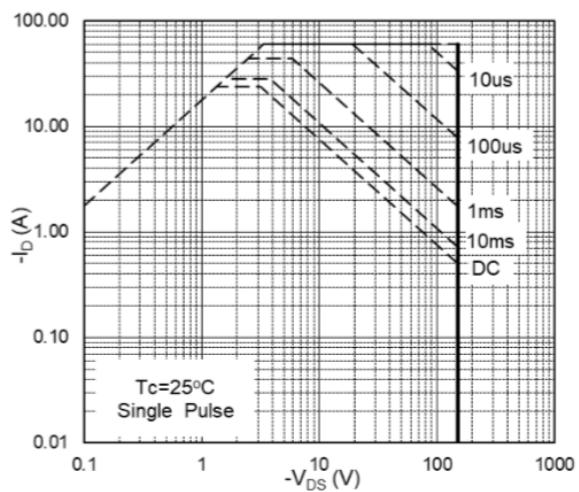


Fig.8 Safe Operating Area

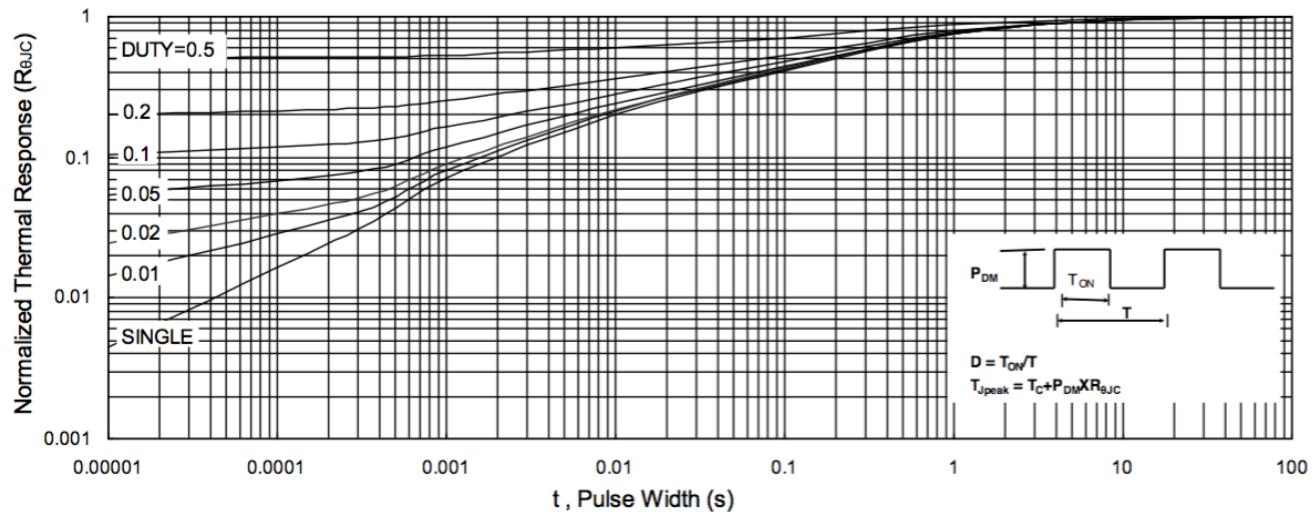


Fig.9 Normalized Maximum Transient Thermal Impedance

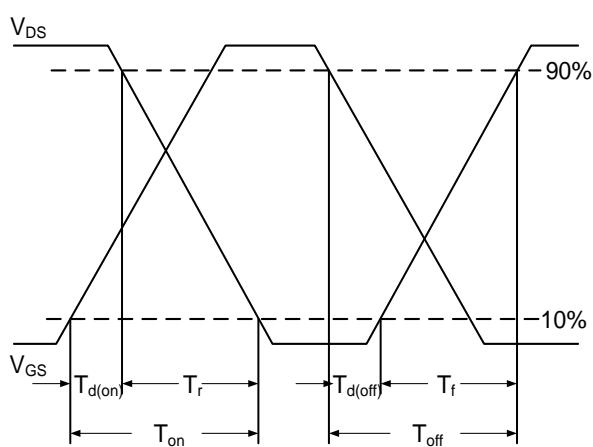


Fig.10 Switching Time Waveform

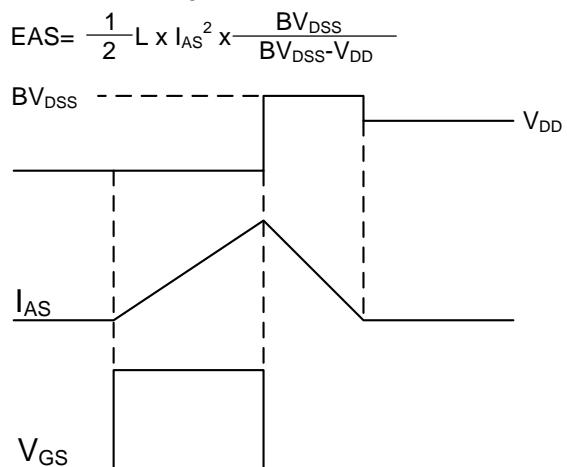


Fig.11 Unclamped Inductive Switching



Ordering Information

| Part Number | Package code | Packaging |
|-------------|--------------|----------------|
| HSM10N15A | SOP-8 | 2500/Tape&Reel |

